

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJ2101
Package Type :	SOT-323

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	2.47%
Lead Frame	Copper	7440-50-8	0.10%	25.35%
	Silicon	7440-21-3	0.20%	
	Manganese	7439-96-5	0.40%	
	Nickel	7440-02-0	41.00%	
	Cobalt	7440-48-4	0.30%	
	Iron	7439-89-6	57.90%	
	Phosphorus	7723-14-0	0.01%	
	Carbon	7440-44-0	0.01%	
	Sulfur	7704-34-9	0.01%	
	Chromium	7440-47-3	0.05%	
Epoxy	Silver	7440-22-4	85.00%	0.16%
	Resins(Urethane/Epoxy)	Trade Secret	8.00%	
	Additives	Trade Secret	7.00%	
Wire	Copper	7440-50-8	99.995%	0.30%
	Others	N/A	0.005%	
Mold Compound	Sillicon Dioxide	7631-86-9	68.00%	69.21%
	Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	15.00%	
	Phenol-formaldehyde polymer	9003-35-4	5.50%	
	Boron zinc hydroxide oxide (B12Zn4(OH)14O15)	138265-88-0	5.00%	
	1,3,5-triazine-2,4,6(1H,3H,5H)-trione, compound with 1,3,5-triazine-2,4,6-triamine (1:1)	37640-57-6	5.00%	
	zinc oxide	1314-13-2	0.50%	
	3-Trimethoxysilylpropane-1-thiol	4420-74-0	0.50%	
Carbon black	1333-86-4	0.50%		
Plating	Tin	7440-31-5	99.90%	2.51%
	Other	NA	0.10%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.